

# Bakelite® PF 7595

Phenolic

Hexion Inc.

## Message:

### Product Description

Phenolic moulding compound, inorganically/organically filled, modified with graphite, good heat conductivity, good sliding properties, conductive in electrical properties

### Application Areas

Bearers for grinding disc centers, gas meter parts, pump parts, sliding/guiding elements, glide bearing parts

| General Information                  |                         |       |             |
|--------------------------------------|-------------------------|-------|-------------|
| Filler / Reinforcement               | Graphite Fiber          |       |             |
|                                      | Organic\Inorganic       |       |             |
| Features                             | Electrically Conductive |       |             |
|                                      | Low Friction            |       |             |
|                                      | Thermally Conductive    |       |             |
| Uses                                 | Bearings                |       |             |
|                                      | Pump Parts              |       |             |
| Processing Method                    | Compression Molding     |       |             |
|                                      | Injection Molding       |       |             |
| Physical                             | Nominal Value           | Unit  | Test Method |
| Density (23°C)                       | 1.59                    | g/cm³ | ISO 1183    |
| Apparent Density                     | 0.85                    | g/cm³ | ISO 60      |
| Molding Shrinkage                    |                         |       | ISO 2577    |
| -- 1                                 | 0.20                    | %     |             |
| -- 2                                 | 0.25                    | %     |             |
| Water Absorption - 24h/23C           | 6.0                     | mg    | ISO 62      |
| Post Shrinkage                       |                         |       | ISO 2577    |
| -- 3                                 | 0.10                    | %     |             |
| -- 4                                 | 0.10                    | %     |             |
| Compression Molding Molding Pressure | > 15.0                  | MPa   |             |
| Compression Molding Temperature      | 160 to 190              | °C    |             |
| Hardness                             | Nominal Value           | Unit  | Test Method |
| Ball Indentation Hardness (H 961/30) | 440                     | MPa   | ISO 2039-1  |
| Mechanical                           | Nominal Value           | Unit  | Test Method |
| Tensile Modulus                      | 12000                   | MPa   | ISO 527-2/1 |
| Tensile Stress                       | 45.0                    | MPa   | ISO 527-2/5 |

|                                                   |               |                   |             |
|---------------------------------------------------|---------------|-------------------|-------------|
| Flexural Modulus                                  | 12000         | MPa               | ISO 178     |
| Flexural Stress <sup>5</sup>                      | 80.0          | MPa               | ISO 178     |
| Compressive Stress                                | 250           | MPa               | ISO 604     |
| Impact                                            | Nominal Value | Unit              | Test Method |
| Charpy Unnotched Impact Strength (23°C)           | 3.5           | kJ/m <sup>2</sup> | ISO 179/1eU |
| Thermal                                           | Nominal Value | Unit              | Test Method |
| Heat Deflection Temperature (8.0 MPa, Unannealed) | 170           | °C                | ISO 75-2/C  |
| Injection                                         | Nominal Value | Unit              |             |
| Rear Temperature                                  | 60.0 to 75.0  | °C                |             |
| Nozzle Temperature                                | 80.0 to 100   | °C                |             |
| Processing (Melt) Temp                            | 80.0 to 100   | °C                |             |
| Mold Temperature                                  | 160 to 190    | °C                |             |
| Injection Pressure                                | > 15.0        | MPa               |             |
| Back Pressure                                     | 0.500 to 2.00 | MPa               |             |
| NOTE                                              |               |                   |             |
| 1.                                                | Compression   |                   |             |
| 2.                                                | Injection     |                   |             |
| 3.                                                | Injection     |                   |             |
| 4.                                                | Compression   |                   |             |
| 5.                                                | 2.0 mm/min    |                   |             |

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